

L Number	Hits	Search Text	DB	Time stamp
1	1090	thermally adj conductive adj adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/02 12:25
2	362	(thermally adj conductive adj adhesive) and (257/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/02 12:25
3	230	((thermally adj conductive adj adhesive) and (257/\$.ccls.)) and (chip die IC) and (heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/02 15:03
4	241	257/700,758,706-707,712-713,717,720,723-724, and core and open\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/02 15:42
5	4	((("6271469") or ("6117704"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/02 13:32
6	14	("3740920"   "4705917"   "4925024"   "5353498"   "5414214"   "5422513"   "5497033"   "5527741"   "5703400"   "5745984"   "5790378"   "5894107"   "6154366"   "6192578").PN. ("5478781"   "5952725").PN.	USPAT	2003/01/02 13:32
7	2	6117704.URPN.	USPAT	2003/01/02 13:34
8	1	174/52.4	USPAT	2003/01/02 13:34
9	3114	174/52.4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/02 15:04
10	16	174/52.4.ccls. and (core plate) with open\$4 with (chip die IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/02 15:07
11	24	174/52.1-52.4.ccls. and (core plate) with open\$4 with (chip die IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/02 15:09
12	2	("6117704").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/02 15:26
13	49	257/700,758,706-707,712-713,717,720,723-724, and core with (heat adj (sink plate plug element spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/02 17:09
14	10	("3374537"   "3480836"   "3646246"   "3833838"   "4320438"   "4404059"   "4472876"   "4595945"   "4654694"   "4663649").PN. ("4731700").PN.	USPAT	2003/01/02 15:53
17	2	174/52.4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/02 18:43

18	2	("6407334").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/02 18:43
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